

International IR Rectifier

RADIATION HARDENED POWER MOSFET THRU-HOLE (TO-39)

PD-97311

IRHF67230
200V, N-CHANNEL
R₆ TECHNOLOGY

Product Summary

Part Number	Radiation Level	R _{DS(on)}	I _D
IRHF67230	100K Rads (Si)	0.145Ω	9.1A
IRHF63230	300K Rads (Si)	0.145Ω	9.1A

International Rectifier's R6™ technology provides superior power MOSFETs for space applications. These devices have improved immunity to Single Event Effect (SEE) and have been characterized for useful performance with Linear Energy Transfer (LET) up to 90MeV/(mg/cm²). Their combination of very low R_{DS(on)} and faster switching times reduces power loss and increases power density in today's high speed switching applications such as DC-DC converters and motor controllers. These devices retain all of the well established advantages of MOSFETs such as voltage control, ease of paralleling and temperature stability of electrical parameters.



TO-39

Features:

- Low R_{DS(on)}
- Fast Switching
- Single Event Effect (SEE) Hardened
- Low Total Gate Charge
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Ceramic Package
- Light Weight

Absolute Maximum Ratings

Pre-Irradiation

	Parameter		Units
I _D @ V _{GS} = 12V, T _C = 25°C	Continuous Drain Current	9.1	A
I _D @ V _{GS} = 12V, T _C = 100°C	Continuous Drain Current	5.7	
I _{DM}	Pulsed Drain Current ①	36.4	
P _D @ T _C = 25°C	Max. Power Dissipation	25	W
	Linear Derating Factor	0.2	W/°C
V _{GS}	Gate-to-Source Voltage	±20	V
E _{AS}	Single Pulse Avalanche Energy ②	23	mJ
I _{AR}	Avalanche Current ①	9.1	A
E _{AR}	Repetitive Avalanche Energy ①	2.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.8	V/ns
T _J	Operating Junction	-55 to 150	°C
T _{STG}	Storage Temperature Range		
	Lead Temperature	300 (0.063in/1.6mm from case for 10s)	
	Weight	0.98 (Typical)	g

For footnotes refer to the last page

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Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

	Parameter	Min	Typ	Max	Units	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	200	—	—	V	V _{GS} = 0V, I _D = 1.0mA
ΔBV _{DSS} /ΔT _J	Temperature Coefficient of Breakdown Voltage	—	0.22	—	V/°C	Reference to 25°C, I _D = 1.0mA
R _{DS(on)}	Static Drain-to-Source On-State Resistance	—	—	0.145	Ω	V _{GS} = 12V, I _D = 5.7A ④
V _{GS(th)}	Gate Threshold Voltage	2.0	—	4.0	V	V _{DS} = V _{GS} , I _D = 1.0mA
ΔV _{GS(th)} /ΔT _J	Gate Threshold Voltage Coefficient	—	-9.6	—	mV/°C	
g _{fs}	Forward Transconductance	5.0	—	—	S	V _{DS} = 15V, I _{DS} = 5.7A ④
I _{DSS}	Zero Gate Voltage Drain Current	—	—	10	μA	V _{DS} = 160V, V _{GS} = 0V
		—	—	25		V _{DS} = 160V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	V _{GS} = 20V
I _{GSS}	Gate-to-Source Leakage Reverse	—	—	-100		V _{GS} = -20V
Q _g	Total Gate Charge	—	—	45	nC	V _{GS} = 12V, I _D = 9.1A
Q _{gs}	Gate-to-Source Charge	—	—	12		V _{DS} = 100V
Q _{gd}	Gate-to-Drain ('Miller') Charge	—	—	30		
t _{d(on)}	Turn-On Delay Time	—	—	17	ns	V _{DD} = 100V, I _D = 9.1A, V _{GS} = 12V, R _G = 7.5Ω
t _r	Rise Time	—	—	30		
t _{d(off)}	Turn-Off Delay Time	—	—	40		
t _f	Fall Time	—	—	25		
LS + LD	Total Inductance	—	7.0	—	nH	Measured from Drain lead (6mm/0.25in from package) to Source lead (6mm/0.25in from package) with Source wire interannally bonded from Source pin to Drain pad
C _{iss}	Input Capacitance	—	1374	—	pF	V _{GS} = 0V, V _{DS} = 25V
C _{oss}	Output Capacitance	—	214	—		f = 1.0MHz
C _{rss}	Reverse Transfer Capacitance	—	4.2	—		
R _g	Gate Resistance	—	1.1	—	Ω	f = 1.0MHz, open drain

Source-Drain Diode Ratings and Characteristics

	Parameter	Min	Typ	Max	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	9.1	A	
I _{SM}	Pulse Source Current (Body Diode) ①	—	—	36.4		
V _{SD}	Diode Forward Voltage	—	—	1.2	V	T _j = 25°C, I _S = 9.1A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	—	317	ns	T _j = 25°C, I _F = 9.1A, di/dt ≤ 100A/μs
Q _{RR}	Reverse Recovery Charge	—	—	2.91	μC	V _{DD} ≤ 50V ④
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L _S + L _D .				

Thermal Resistance

	Parameter	Min	Typ	Max	Units	Test Conditions
R _{thJC}	Junction-to-Case	—	—	5.0	°C/W	

Note: Corresponding Spice and Saber models are available on International Rectifier Web site.

For footnotes refer to the last page

Radiation Characteristics

IRHF67230

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-39 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table 1. Electrical Characteristics @ $T_j = 25^\circ\text{C}$, Post Total Dose Irradiation ⑤⑥

	Parameter	Upto 300K Rads(Si) ¹		Units	Test Conditions ⑧
		Min	Max		
BV_{DSS}	Drain-to-Source Breakdown Voltage	200	—	V	$V_{GS} = 0V, I_D = 1.0mA$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	4.0		$V_{GS} = V_{DS}, I_D = 1.0mA$
I_{GSS}	Gate-to-Source Leakage Forward	—	100	nA	$V_{GS} = 20V$
I_{GSS}	Gate-to-Source Leakage Reverse	—	-100		$V_{GS} = -20V$
I_{DSS}	Zero Gate Voltage Drain Current	—	1.0	μA	$V_{DS} = 200V, V_{GS} = 0V$
$R_{DS(on)}$	Static Drain-to-Source ④ On-State Resistance (TO-39)	—	0.145	Ω	$V_{GS} = 12V, I_D = 5.7A$
V_{SD}	Diode Forward Voltage ④	—	1.2	V	$V_{GS} = 0V, I_D = 9.1A$

1. Part numbers IRHF67230, IRHF63230

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Typical Single Event Effect Safe Operating Area

LET (MeV/(mg/cm ²))	Energy (MeV)	Range (μm)	VDS (V)			
			@VGS=0V	@VGS=-5V	@VGS=-10V	@VGS=-15V
42 $\pm$ 5%	2450 $\pm$ 5%	205 $\pm$ 5%	200	200	200	190
61 $\pm$ 5%	825 $\pm$ 5%	66 $\pm$ 7.5%	200	200	200	190
90 $\pm$ 5%	1470 $\pm$ 5%	80 $\pm$ 5%	170	170	-	-

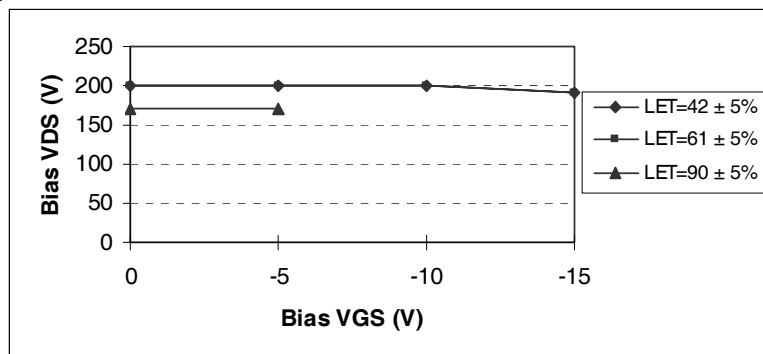


Fig a. Typical Single Event Effect, Safe Operating Area

For footnotes refer to the last page

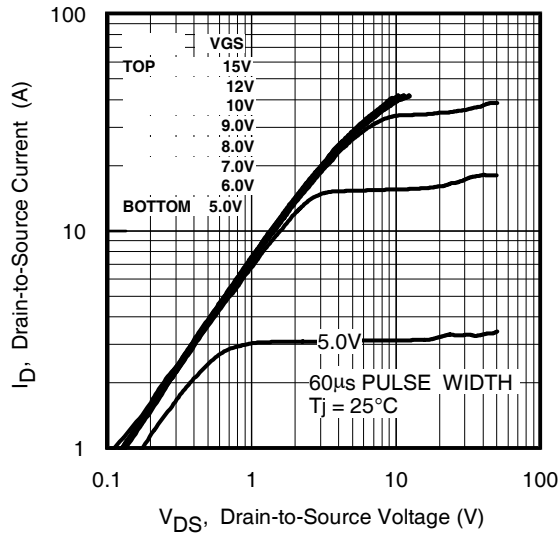


Fig 1. Typical Output Characteristics

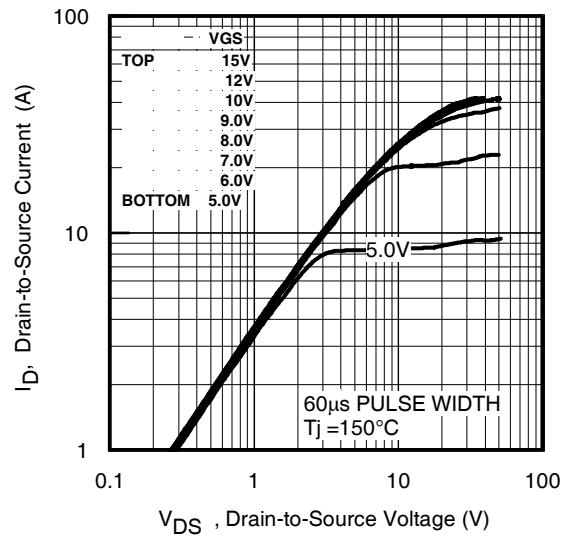


Fig 2. Typical Output Characteristics

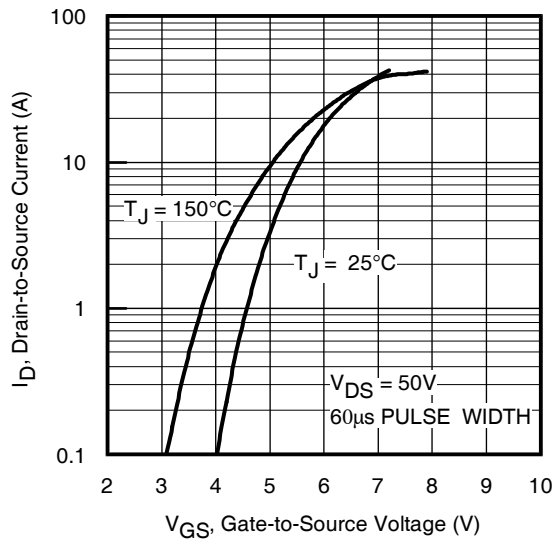


Fig 3. Typical Transfer Characteristics

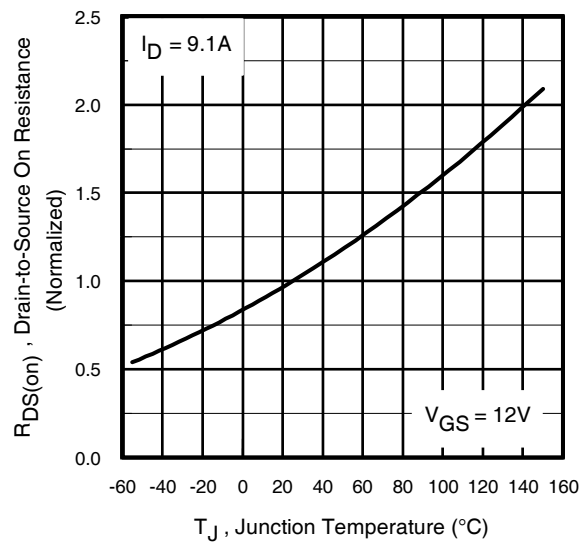


Fig 4. Normalized On-Resistance Vs. Temperature

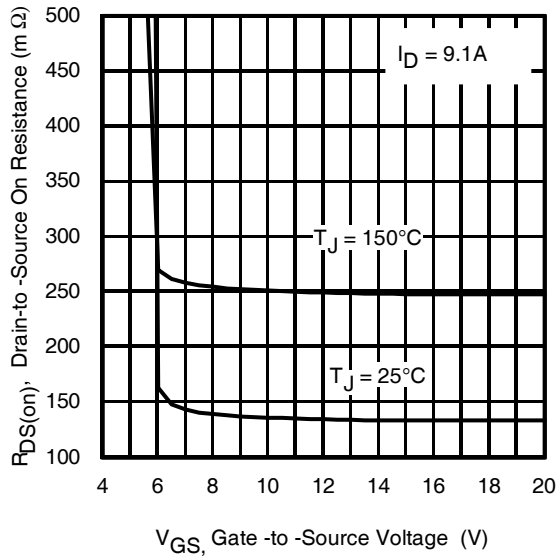


Fig 5. Typical On-Resistance Vs Gate Voltage

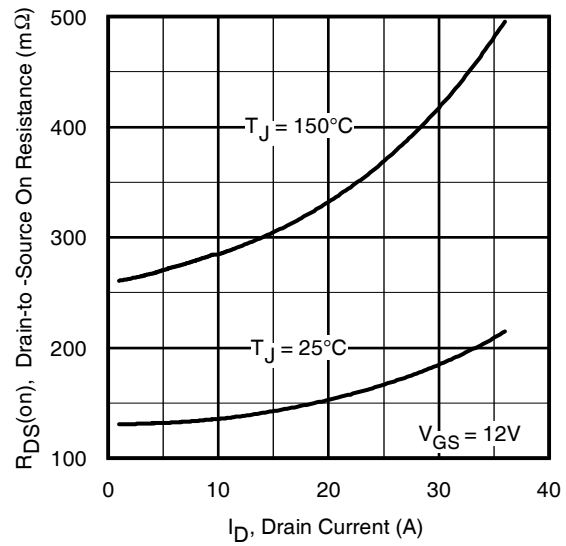


Fig 6. Typical On-Resistance Vs Drain Current

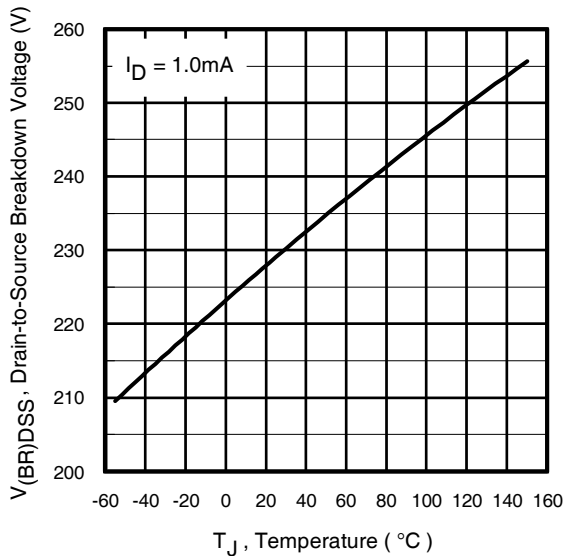


Fig 7. Typical Drain-to-Source Breakdown Voltage Vs Temperature

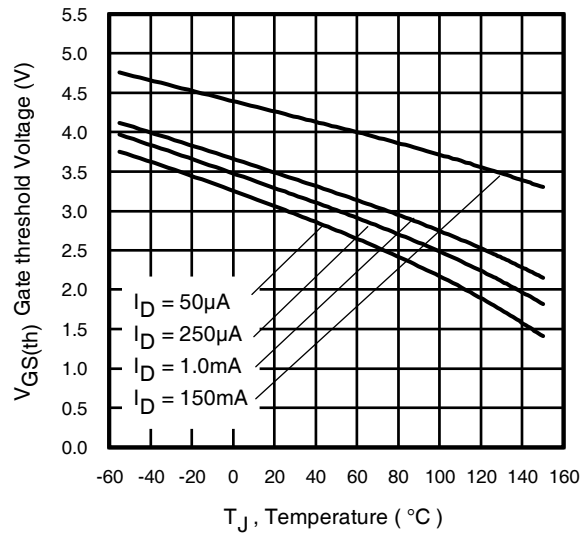


Fig 8. Typical Threshold Voltage Vs Temperature

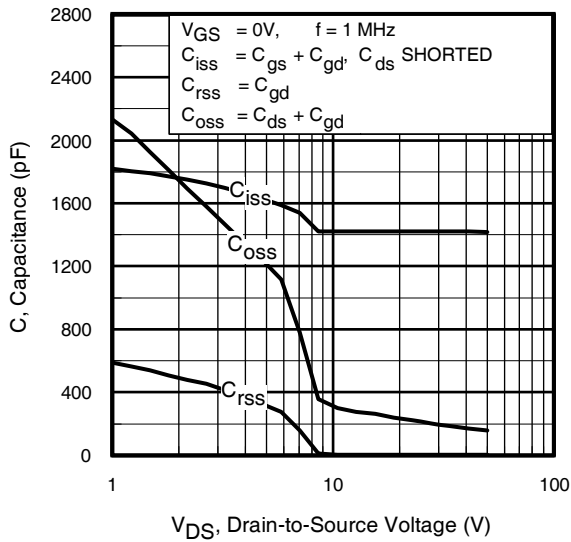


Fig 9. Typical Capacitance Vs. Drain-to-Source Voltage

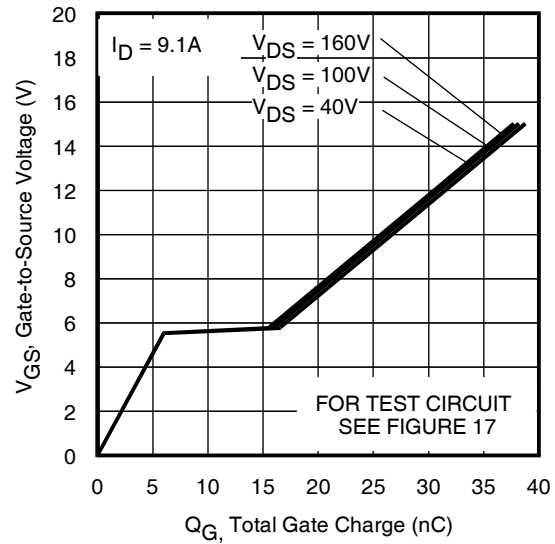


Fig 10. Typical Gate Charge Vs. Gate-to-Source Voltage

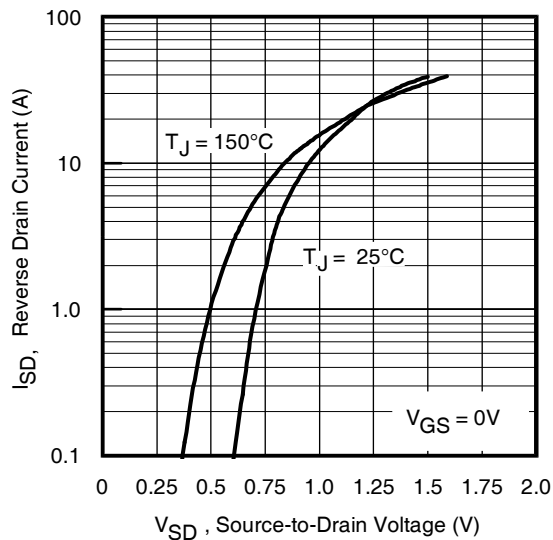


Fig 11. Typical Source-Drain Diode Forward Voltage

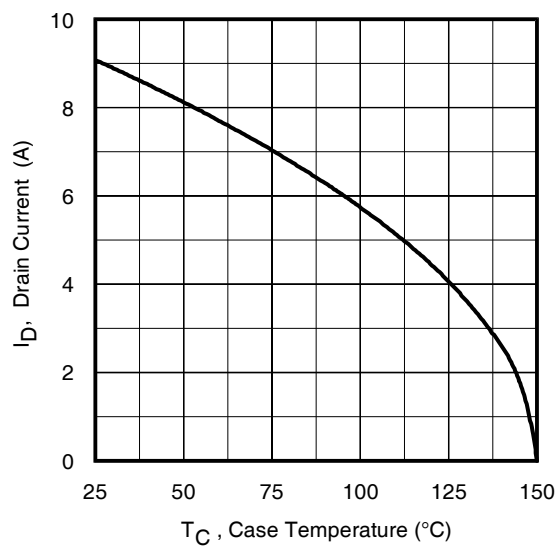


Fig 12. Maximum Drain Current Vs. Case Temperature

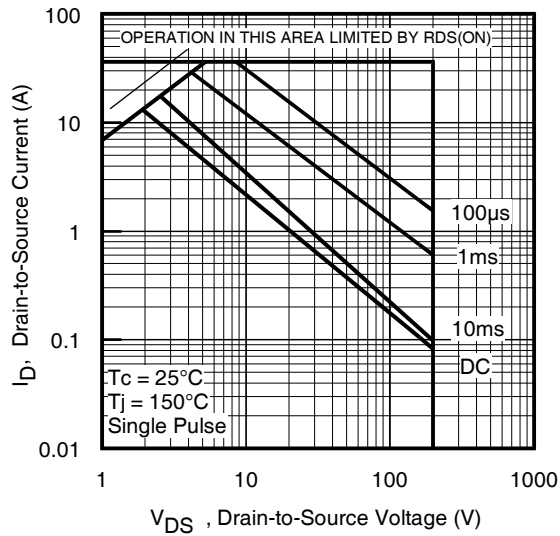


Fig 13. Maximum Safe Operating Area

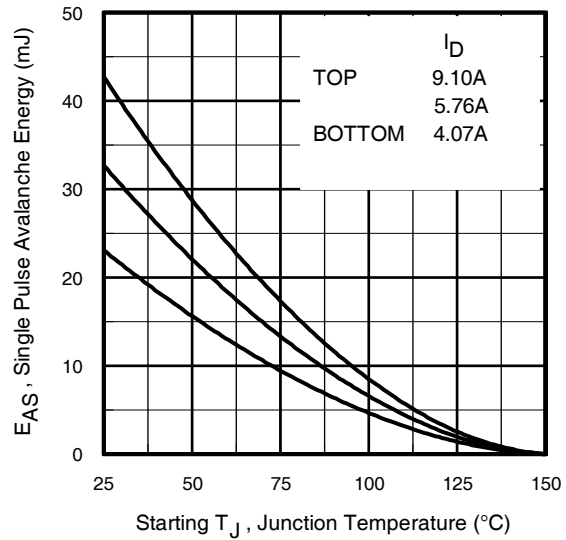


Fig 14. Maximum Avalanche Energy Vs. Drain Current

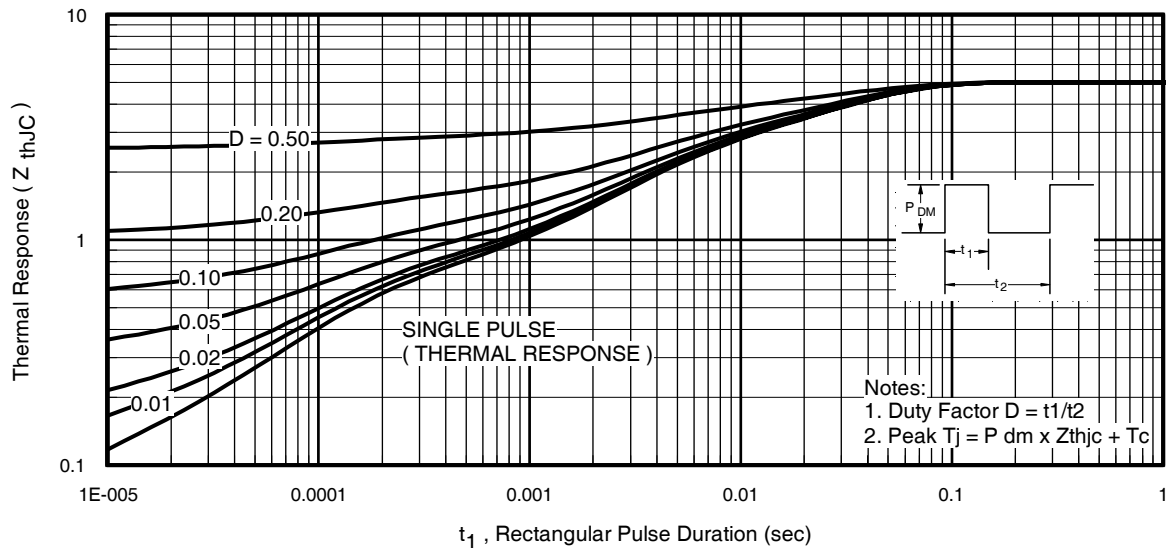


Fig 15. Maximum Effective Transient Thermal Impedance, Junction-to-Case

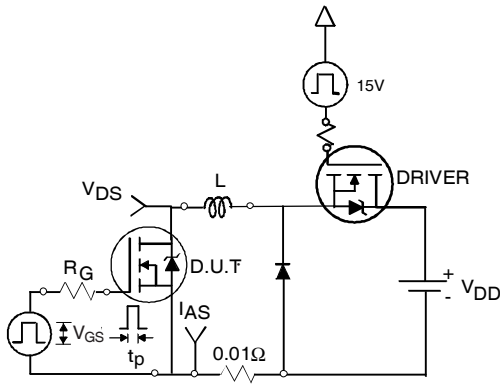


Fig 16a. Unclamped Inductive Test Circuit

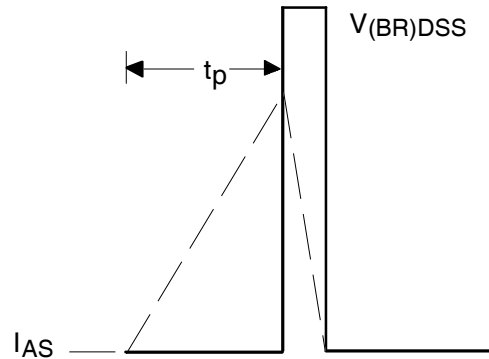


Fig 16b. Unclamped Inductive Waveforms

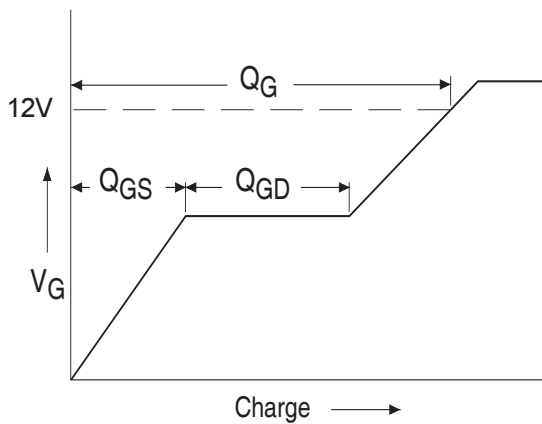


Fig 17a. Basic Gate Charge Waveform

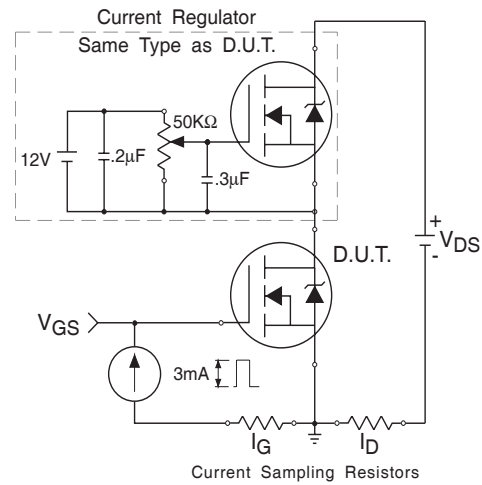


Fig 17b. Gate Charge Test Circuit

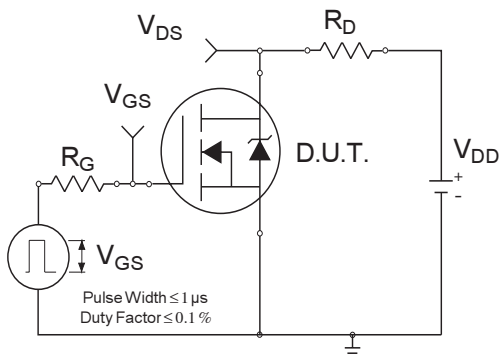


Fig 18a. Switching Time Test Circuit

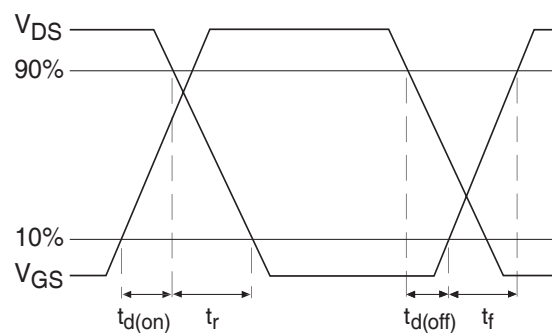
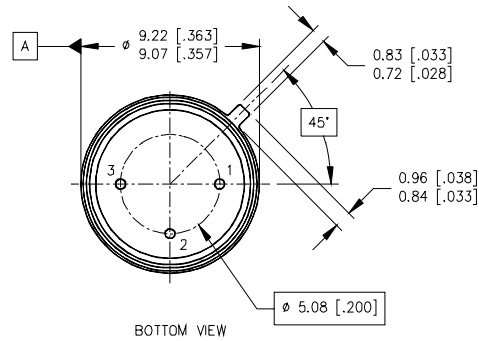


Fig 18b. Switching Time Waveforms

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② $V_{DD} = 50V$, starting $T_J = 25^{\circ}C$, $L = 0.56mH$
Peak $I_L = 9.1A$, $V_{GS} = 12V$
- ③ $I_{SD} \leq 9.1A$, $di/dt \leq 347A/\mu s$,
 $V_{DD} \leq 200V$, $T_J \leq 150^{\circ}C$

- ④ Pulse width $\leq 300 \mu\text{s}$; Duty Cycle $\leq 2\%$
- ⑤ **Total Dose Irradiation with V_{GS} Bias.**
12 volt V_{GS} applied and $V_{DS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with V_{DS} Bias.**
160 volt V_{DS} applied and $V_{GS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.

Side view of a mechanical part. The part consists of a base plate with three vertical pins. The base plate has a width of 8.30 [.327] and a thickness of 0.45 [.018] and 0.36 [.014]. The pins are 14.22 [.560] high and have a diameter of 0.48 [.019] and 0.41 [.016]. The base plate has a total height of 18.03 [.710] and a width of 8.18 [.322]. The pins are 12.70 [.500] high. The part is labeled with a feature control frame: $\varnothing$ 0.36 [.014] M B A M.



1. DIMENSIONING AND TOLERANCING PER ASME 14.5M-1994.
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. CONTROLLING DIMENSION: INCH.
4. CONFORMS TO JEDEC OUTLINE TO-205AF (TO-39).

1 - SOURCE
2 - GATE
3 - DRAIN

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Data and specifications subject to change without notice. 09/2011